



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



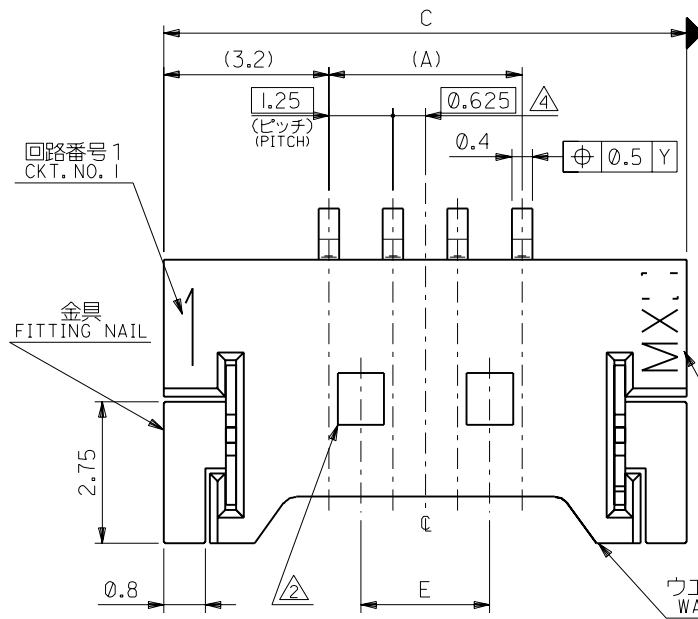
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

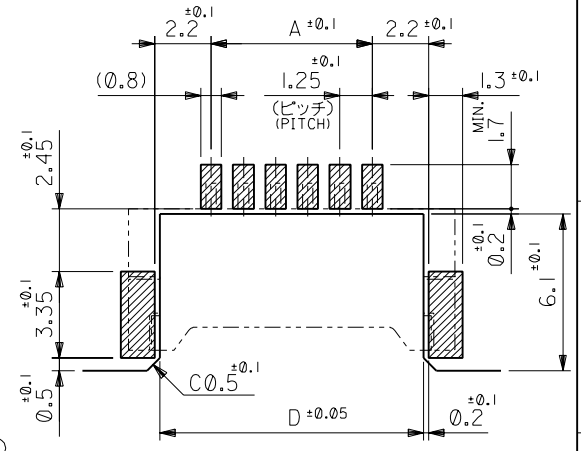
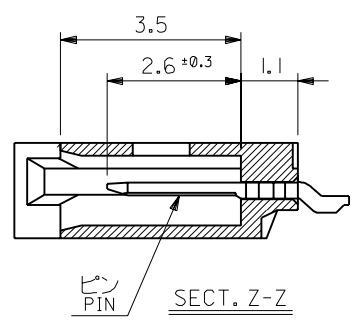
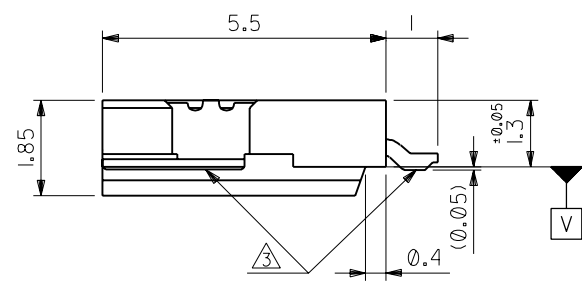
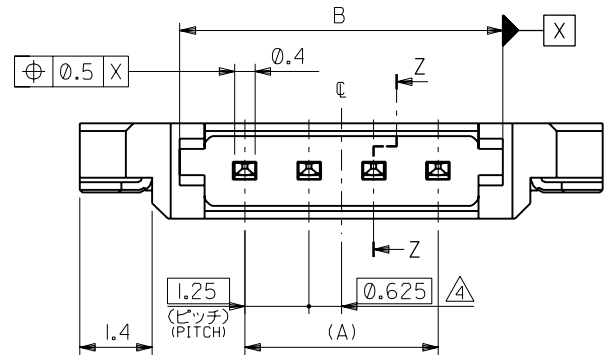




注記 NOTES

1. 嵌合相手 : 51146 シリーズ
MATES WITH : 51146 SERIES
2. ロック窓は2、3極品は1箇所、4極品以上は2箇所とする。
LOCKING WINDOW : ONE PLACE FOR 2 AND 3 CIRCUIT PRODUCTS AND TWO PLACES FOR MORE THAN 3 CIRCUIT PRODUCTS.
3. 基準面 [V] からのソルダーテールと金具の半田付け面のズレ量は、上方に 0.05MAX. 、下方に 0.15MAX. 、とし、相互のバラつき量は 0.1MAX. とする。
MISALIGNMENT OF SOLDER TAIL AND FITTING NAIL FROM [V] : UPPER DIRECTION 0.05MAX. : LOWER DIRECTION 0.15MAX. : OFFSET BETWEEN UPPER AND LOWER 0.1MAX.
4. 偶数極の製品に適用。
APPLY EVEN CIRCUIT PRODUCTS.
5. 材質 MATERIAL
ウエハー WAFER : PPHS , UL94V-0
ピン : リン青銅 (コンタクト部 : 金メッキ、テール部 : 半田メッキ)
PIN : PHOS-BRO (CONTACT : Au PLATING, TAIL : Sn-Pb PLATING)
金具 : リン青銅 (半田メッキ)
FITTING NAIL : PHOS-BRO (Sn-Pb PLATING)

トレードマーク TRADE MARK



参考基板レイアウト RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)

16.25	22.5	40.25	42.65	38.77	36.25	53779-3010	30
15	22.5	37.75	40.15	36.27	33.75		-2810 28
13.75	22.5	35.25	37.65	33.77	31.25		-2610 26
12.5	22.5	32.75	35.15	31.27	28.75		-2410 24
11.25	22.5	30.25	32.65	28.77	26.25		-2210 22
8.75	22.5	27.75	30.15	26.27	23.75		-2010 20
7.5	20	25.25	27.65	23.77	21.25		-1810 18
6.25	17.5	22.75	25.15	21.27	18.75		-1610 16
6.25	16.25	21.5	23.9	20.02	17.5		-1510 15
5	15	20.25	22.65	18.77	16.25		-1410 14
3.75	12.5	17.75	20.15	16.27	13.75		-1210 12
2.5	10	15.25	17.65	13.77	11.25		-1010 10
2.5	8.75	14	16.4	12.52	10		-0910 9
1.25	7.5	12.75	15.15	11.27	8.75		-0810 8
1.25	6.25	11.5	13.9	10.02	7.5		-0710 7
--	5	10.25	12.65	8.77	6.25		-0610 6
--	3.75	9	11.4	7.52	5		-0510 5
--	2.5	7.75	10.15	6.27	3.75		-0410 4
--	--	6.5	8.9	5.02	2.5		-0310 3
--	--	5.25	7.65	3.77	1.25	53779-0210	2
F	E	D	C	B	A	ENG. NO.	CKT. 極数

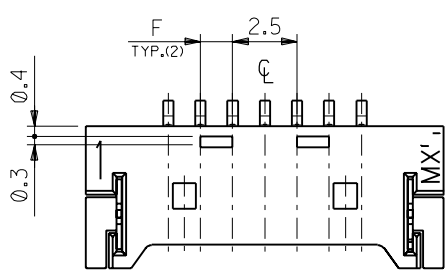
G	変更 REVISD (JC2001-0899)	S.M.T.Y	01/5/11	材料 MATERIAL 注記参照 SEE NOTES
F	変更 REVISD (JC809191)	S.M.S.K	98/6/7	
E	変更 REVISD (JC80823)	S.M.S.K	98/4/22	
D	変更 REVISD (JC70592)	S.M.Y.M	97/1/9	
C	変更 REVISD (JC70159)	S.M.Y.M	96/8/9	
B	変更 REVISD (JC60804)	S.M.M.F	96/5/1	仕上げ FINISH --
A	変更 REVISD (JC60541)	S.M.H.H	96/2/6	
0	新規格作成 PROPOSED (JC60428)	Y.M.H.H	95/12/25	被覆外径 INS. RANGE --
記号 LTR	変更内容 REVISION RECORD	DR. CHK.	日付 DATE	DRAWN BY '01/05/11 S.MATSUZAKI T.YAMAGUCHI
一般公差 GENERAL TOLERANCES				CHK'D BY '01/05/11 T.YAMAGUCHI
				APP'D BY '01/05/11 尺度 SCALE --

molex MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

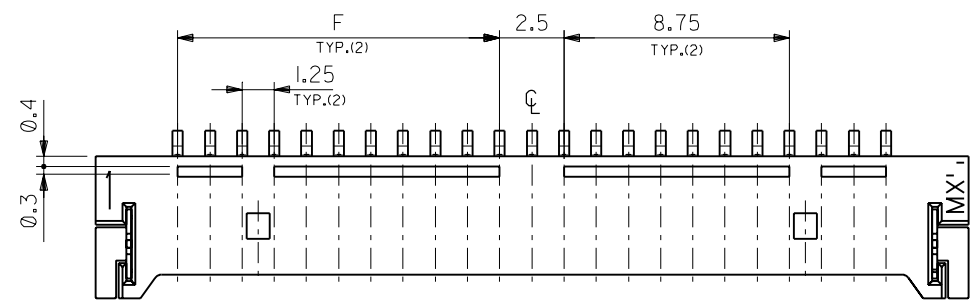
REVISE ONLY ON CAD SYSTEM

TITLE 名称
1.25 WIRE TO BOARD CONN.
WAFER ASS'Y FOR S.M.T.
(H=1.35)

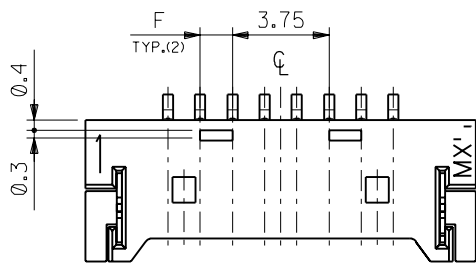
DWG. NO. (SHEET 1 OF 2) REV
SD-53779-***10 G



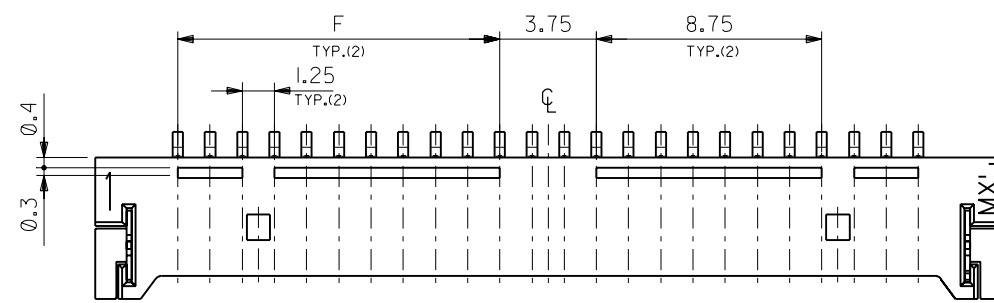
7~19極の奇数極に適用
APPLY FOR ODD CIRCUITS OF 7~19



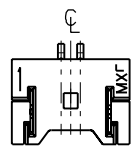
21極以上の奇数極に適用
APPLY FOR ODD CIRCUITS 21~29



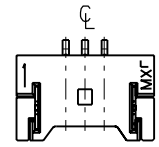
8~20極の偶数極に適用
APPLY FOR EVEN CIRCUITS OF 8~20



22極以上の偶数極に適用
APPLY FOR EVEN CIRCUITS 22~30



2 CKT.



3 CKT.

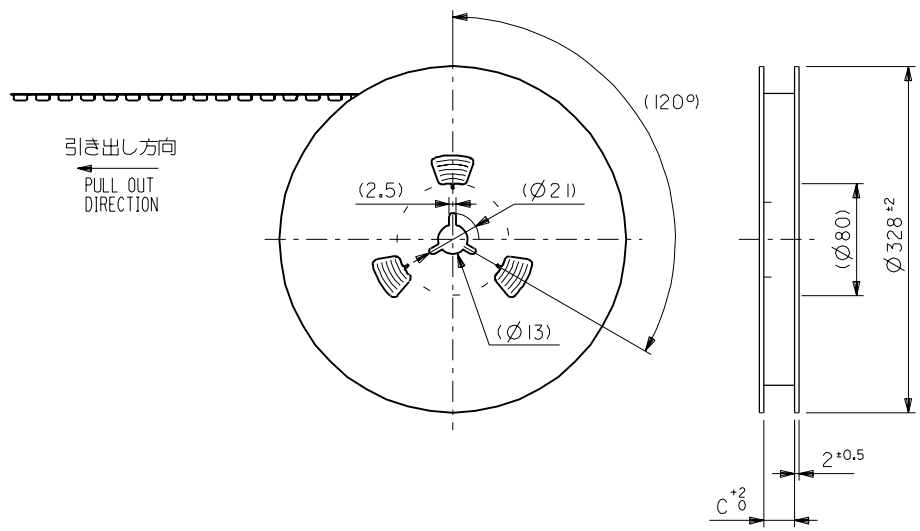
ロック形状図
LOCK CONFIGURATION

角度 ANGLE	±3°	G 変更 (JC2001-0899)	S.M.	T.Y.	'01/5/11	材料 MATERIAL 注記参照 SEE NOTES
30以上 OVER	+0.3	F 変更 (JC80919)	S.M.	S.K.	'98/6/7	
10以上 OVER 30未済 UNDER	+0.25	E 変更 (JC80823)	S.M.	S.K.	'98/4/22	仕上げ FINISH —
未済 UNDER	+0.2	D 変更 (JC70592)	S.M.	Y.M.	'97/1/9	
一般公差 GENERAL TOLERANCES		C 変更 (JC70159)	S.M.	Y.M.	'96/8/9	適用電線範囲 WIRE RANGE —
記号 LTR		B 変更 (JC60804)	S.M.	M.F.	'96/5/1	被覆外径 INS. RANGE —
変更内容 REVISION RECORD		A 変更 (JC60541)	S.M.	H.H.	'96/2/6	
		新規作成 PROPOSED (JC60428)	Y.M.	H.H.	'95/12/25	DRAWN BY '01/05/11 S.MATSUZAKI
			DR. CHK.	DATE		CHK'D BY '01/05/11 T.YAMAGUCHI
						APP'D BY '01/05/11 T.YAMAGUCHI
						尺度 SCALE —

MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称 1.25 WIRE TO BOARD CONN. WAFER ASS'Y FOR S.M.T. (H=1.35)	
DWG. NO. (SHEET 2 OF 2)	REV G
SD-53779-**-10	

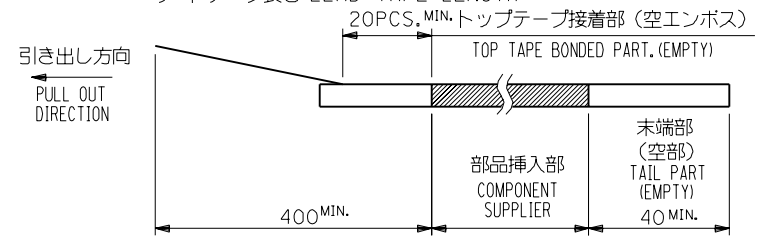
DWG. NO. SD-53779-**-90

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

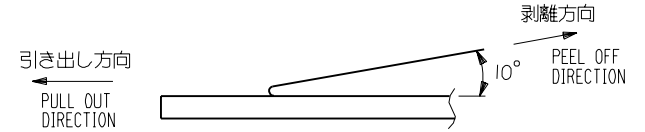


NOTES

- 梱包数量 : 1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度 : 0.1N ~ 0.7N (10.2gf ~ 71.4gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N (10.2gf ~ 71.4gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE) : PET, PE, PEF
リール (REEL) : 紙製 (CARD BOARD)

角度 ANGLE		+3°				材料 MATERIAL	注記参照 SEE NOTE	molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
30 以上 OVER		+0.3				仕上げ FINISH	—	REVISE ONLY ON CAD SYSTEM
10 以上 30 UNDER		+0.25	J	変更 REVISIED (JC90327)	S.M	適用電線範囲 WIRE RANGE	—	TITLE 名称
10 UNDER		+0.2	H	再作図と変更 REDRAWN & REVISED (JC80706)	T.A S.K	被覆外径 INS. RANGE	—	53779-**-10 テーピング梱包 EMBOSSD TAPE PACKAGE FOR 53779-**-10
一般公差 GENERAL TOLERANCES			記号 LTR	変更内容 REVISION RECORD	DR. CHR.	日付 DATE	APP'D BY '98/12/11 M.FUKUSHIMA	DWG. NO. (SHEET 1 OF 3) REV
							尺度 SCALE	SD-53779-**-90 J

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DWG. NO. SD-53779-**-90

F

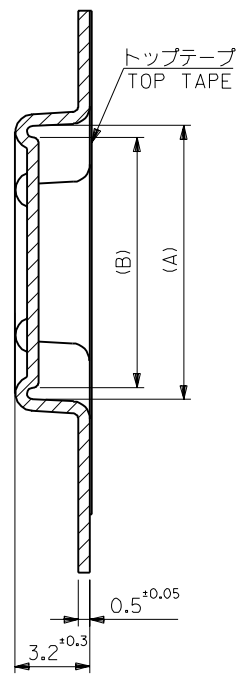
D

C

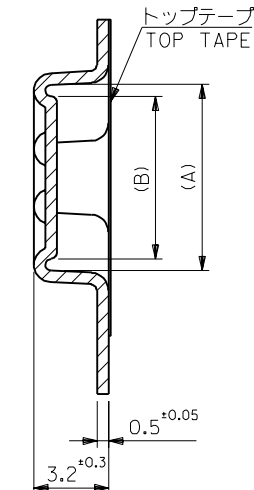
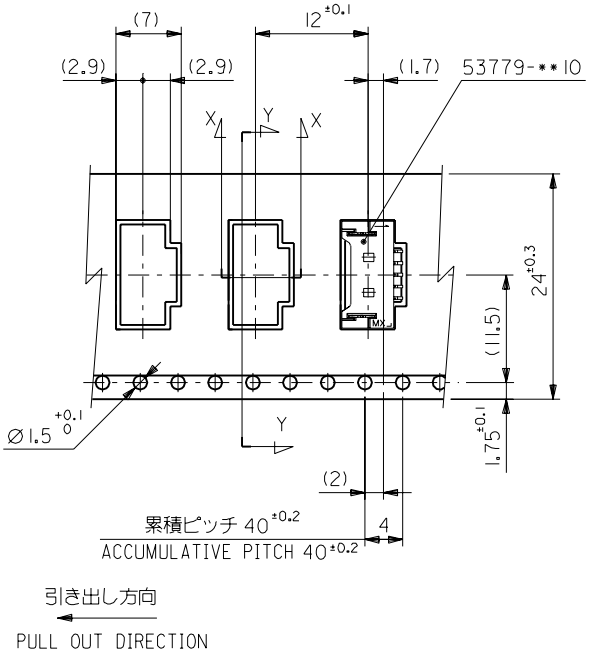
B

A

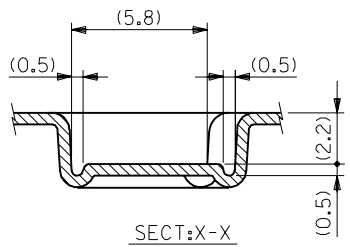
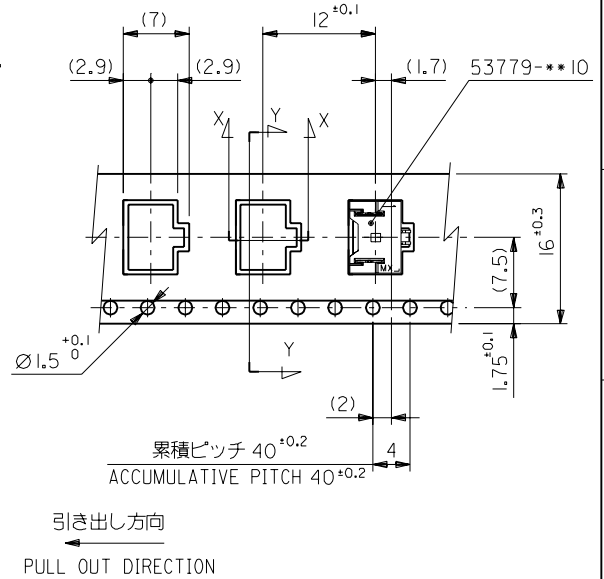
DIMENSIONS IN METRIC DO NOT SCALE DRAWING



SECT:Y-Y
(SCALE 5:1)



SECT:Y-Y
(SCALE 5:1)



SECT:X-X
(SCALE 5:1)

24	24.4	11.75	16.7	53779-0990	9	
		10.5	15.45	53779-0890	8	
		9.25	14.2	53779-0790	7	
		8	12.95	53779-0690	6	
		6.75	11.7	53779-0590	5	
		5.5	10.45	53779-0490	4	
16	16.4	4.25	9.2	53779-0390	3	
		3	7.95	53779-0290	2	
		キャリアテープ幅 CARRIER TAPE WIDTH		C	(B)	(A)

材料 MATERIAL SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3	材料 MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
仕上げ FINISH	REVISE ONLY ON CAD SYSTEM
適用電線範囲 WIRE RANGE	TITLE 名称 53779-**-10 テーピング梱包 EMBOSSD TAPE PACKAGE FOR 53779-**-10
被覆外径 INS. RANGE	DWG. NO. (SHEET 2 OF 3) REV SD-53779-**-90
DRAWN BY '95/12/27 S.MATSUZAKI	CHK'D BY '98/12/1 S.KUNISHI
APP'D BY '98/12/1 M.FUKUSHIMA	尺 度 SCALE
角度 ANGLE	±3°
30 以上 OVER	+0.3
10 以上 30 未満 UNDER	+0.25
未 満 UNDER	+0.2
一般公差 GENERAL TOLERANCES	
記号 LTR	変更内容 REVISION RECORD
J	変更 (JC90327)
H	再作図と変更 REDRAWN & REVISED (JC80706)
	DR. 日付 CHKR. DATE
	S.M. '98/12/1
	T.A. '98/12/1
	S.K. '98/12/1

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F

E

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C

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5377990.S04

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7

6

5

4

3

2

1

DWG. NO. SD-53779-***90

F

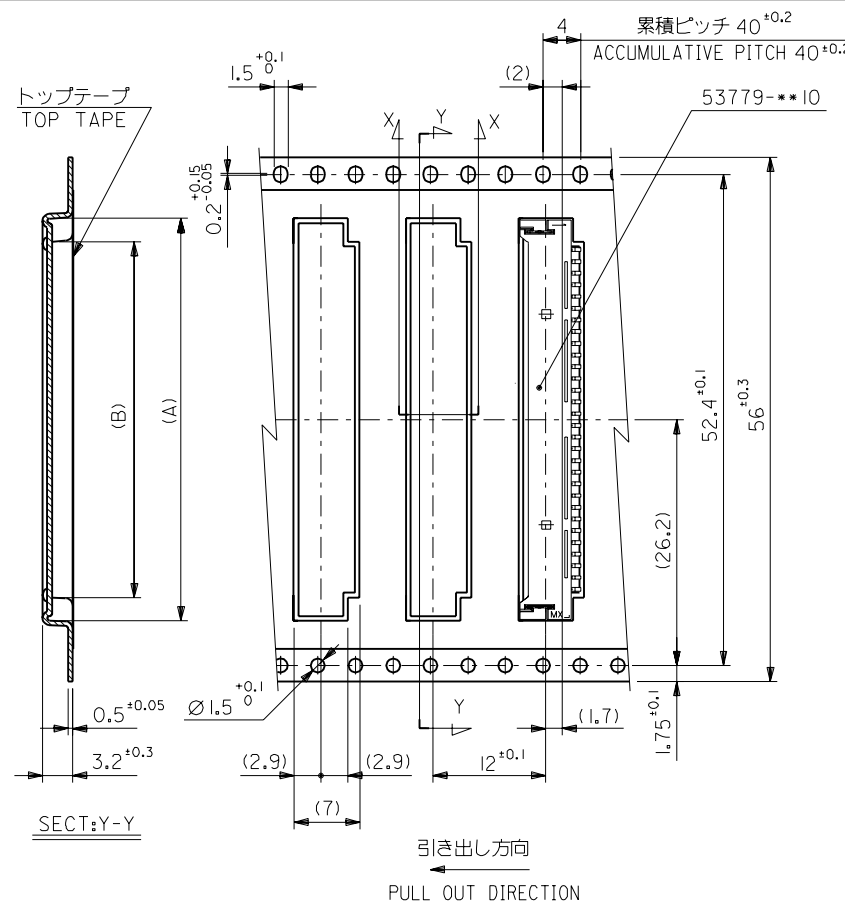
D

C

B

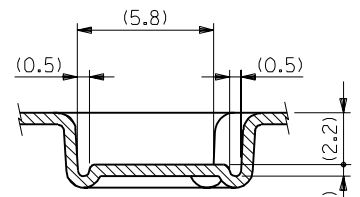
A

DIMENSIONS IN METRIC DO NOT SCALE DRAWING

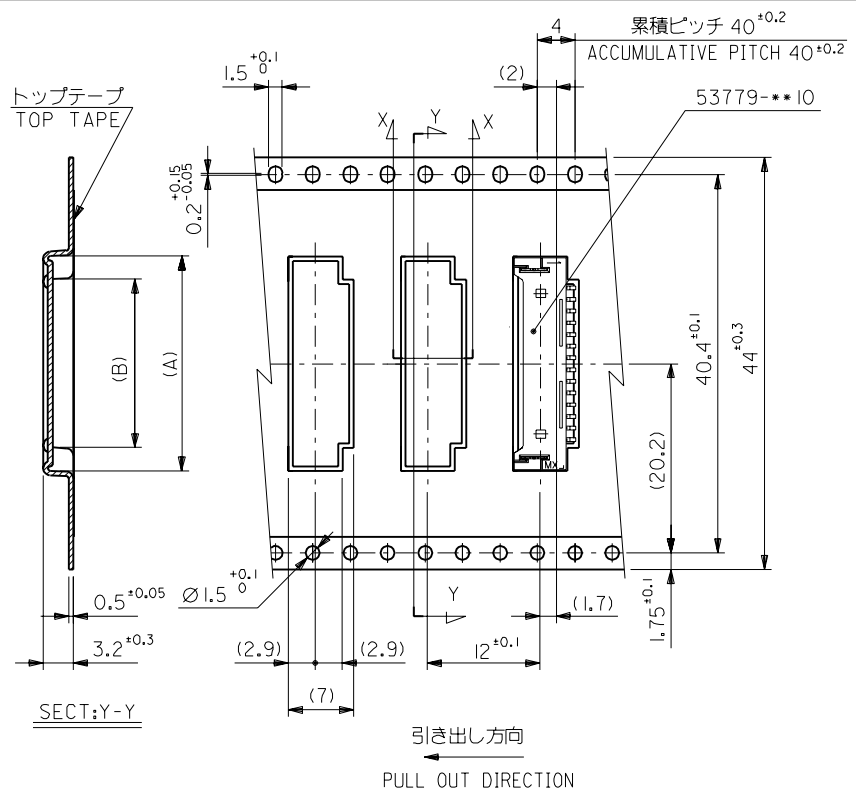


SECT:Y-Y

引き出し方向
PULL OUT DIRECTION



SECT:X-X
(SCALE 5:1)



SECT:Y-Y

引き出し方向
PULL OUT DIRECTION

56	56.4	38	42.95	53779-3090	30
		33	37.95	53779-2690	26
44	44.4	28	32.95	53779-2290	22
		25.5	30.45	53779-2090	20
		19.25	24.2	53779-1590	15
		18	22.95	53779-1490	14
キャリアテープ幅 CARRIER TAPE WIDTH		C	(B)	(A)	種改 CKT.

角度 ANGLE	+3°
30以上 OVER	+0.3
10以上 30未満 UNDER	+0.25
10未満 UNDER	+0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR. CHR.	日付 DATE
J	変更 (JC90327)	S.M.	98/12/11
H	再作図と実装 REDRAWN & REVISED (JC80706)	T.A.	98/3/11

材料 MATERIAL SHEET 1 OF 3 参照 REFER TO SHEET 1 OF 3

仕上げ FINISH #

適用電線範囲 WIRE RANGE #

被覆外径 INS. RANGE #

DRAWN BY '95/12/27 S.MATSUZAKI

CHK'D BY '98/12/11 S.KUNISHI

APP'D BY '98/12/11 M.FUKUSHIMA

尺度 SCALE #

材料 MOLEX JAPAN CO.,LTD. 日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称

53779-***10 テープ梱包
EMBOSSD TAPE PACKAGE
FOR 53779-***10

DWG. NO. (SHEET 3 OF 3) REV SD-53779-***90 J

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E

D

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5377990.S03